# Hybrid 8j35 Traveler

December 16, 1999

## 1 Connectivity

Repairs on shorts:

Fixes for opens:

## 2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J35 has die: 048-011 048-012 048-016 048-017 045-033 045-034 045-035 045-036

## 3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

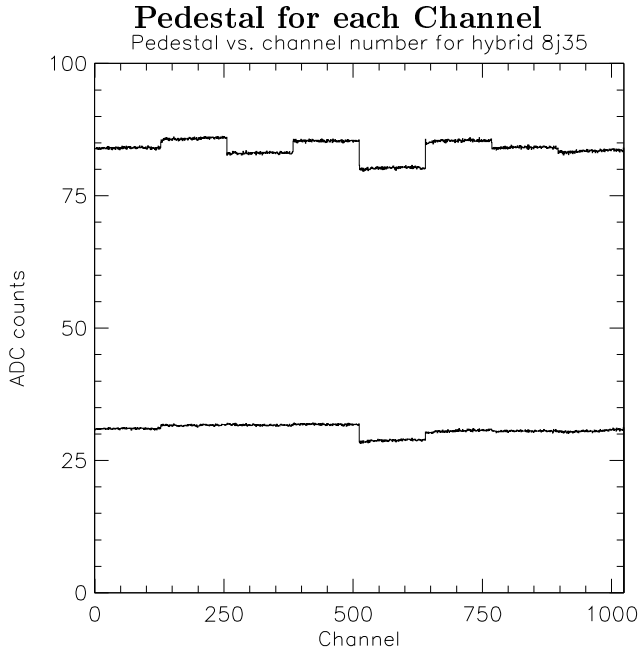
```
% Hybrid 8j35 classification info. Created 10:42:37 12/13/99

Hybrid 8j35 quality: bad
Chip classification: bad good good good good good good good
Bad channels: none
Bad cells: none
Random bad capacitors: none
Channels at pedestal needed for DCMS: 33.6 32.6 34.5 34.6 34.6 35.6 34.6 34.6
```

## 4 Comments

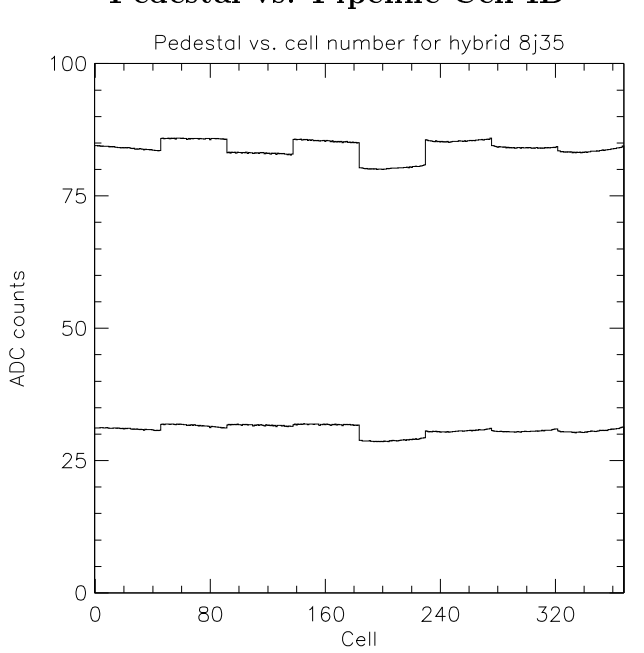
No comments.

# 5 Pedestal

The following plot shows the pedestals vs. channel number with and without charge injection:



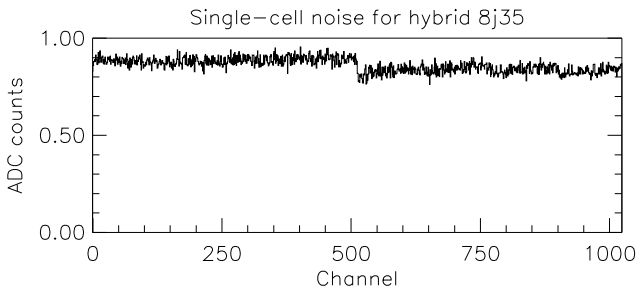

The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

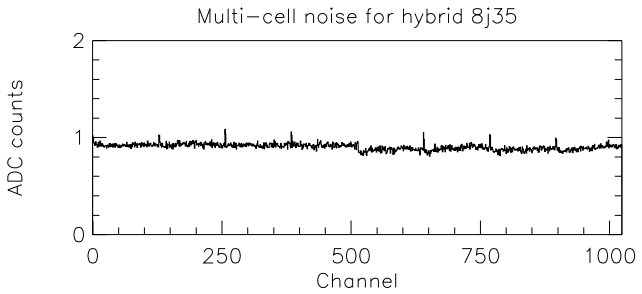


# 6 Noise

The following plots show the single-cell and multi-cell RMS noise:

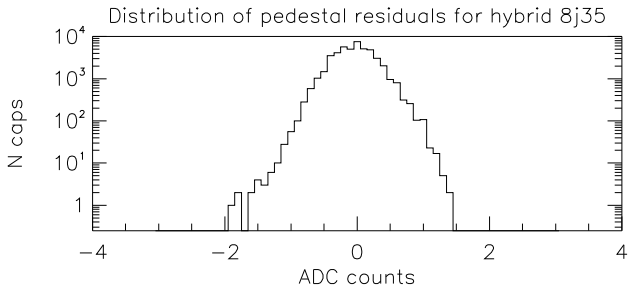
**RMS Noise**

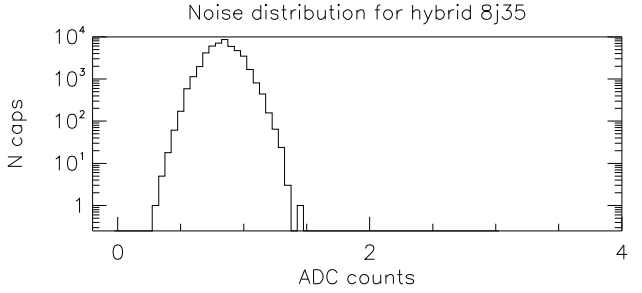


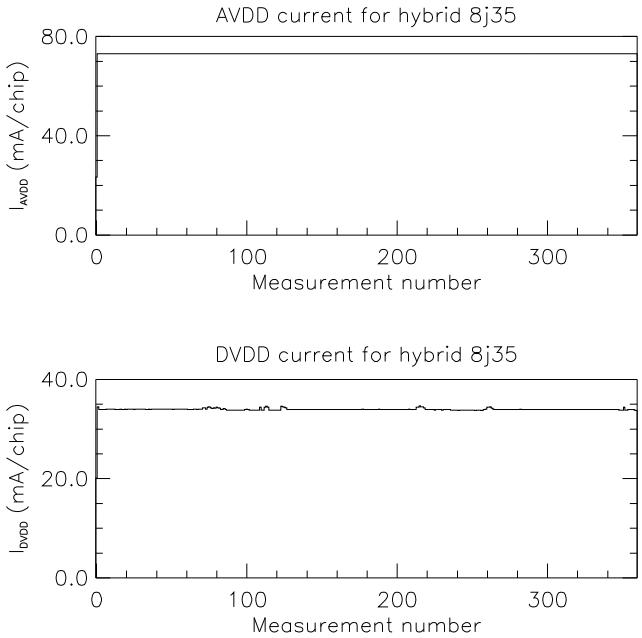

The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

**Distribution of Pedestals and Noise**



# 7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

**Supply Currents During Burn-in**